



Docket No.: 50432-204

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2/12/03
Multi-List
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
Minh Van NGO, et al. :
Serial No.: 09/986,267 : Group Art Unit: 2812
Filed: November 08, 2001 : Examiner: J. Brophy
For: METHOD OF FORMING RELIABLE CU INTERCONNECTS

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AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

The following Amendment and Remarks are submitted in response to the Office Action dated November 1, 2002.

IN THE CLAIMS:

Please amend claim 10 as follows.

10. (Amended) The method according to claim 9, comprising:

treating the upper surface of the Cu or Cu alloy in a plasma containing $[NH_4] NH_3$
to remove copper oxide therefrom; and
depositing a silicon nitride capping layer on the plasma treated surface by plasma
enhanced chemical vapor deposition.

Please add new claim 16 as follows.